

10/078720
02/19/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10078720	FILING DATE 02/19/2002	CLASS 219	SUBCLASS 1212	GAU 1725	EXAMINER Elve
**APPLICANTS: Ye Kaidong; An Chengwu; Hong Minghui; Lu Yongfeng;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>			RESCIND <input type="checkbox"/>		
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			ATTORNEY DOCKET NO		
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			4795-004		
Verified and Acknowledged Examiners's initials <i>KE</i>					
TITLE : Method and apparatus for cutting a substrate using laser irradiation					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH:

☐ DISK (CRF)

☐ CD-ROM

(Attached in pocket on right inside flap)